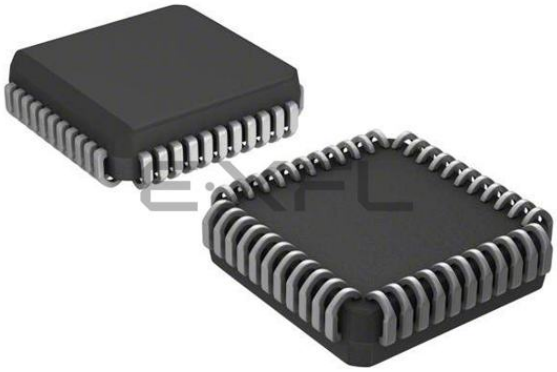

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Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 10x12b
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc774t-l

NOTES:

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2.2.2.2 OPTION_REG REGISTER

The OPTION_REG register is a readable and writable register which contains various control bits to configure the TMR0 prescaler/WDT postscaler (single assignable register known also as the prescaler), the External INT Interrupt, TMR0, and the weak pull-ups on PORTB.

Note: To achieve a 1:1 prescaler assignment for the TMR0 register, assign the prescaler to the Watchdog Timer.

FIGURE 2-4: OPTION_REG REGISTER (ADDRESS 81h, 181h)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **$\overline{\text{RBPU}}$**: PORTB Pull-up Enable bit
1 = PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values

bit 6: **INTEDG**: Interrupt Edge Select bit
1 = Interrupt on rising edge of RB0/INT pin
0 = Interrupt on falling edge of RB0/INT pin

bit 5: **T0CS**: TMR0 Clock Source Select bit
1 = Transition on RA4/T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)

bit 4: **T0SE**: TMR0 Source Edge Select bit
1 = Increment on high-to-low transition on RA4/T0CKI pin
0 = Increment on low-to-high transition on RA4/T0CKI pin

bit 3: **PSA**: Prescaler Assignment bit
1 = Prescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module

bit 2-0: **PS2:PS0**: Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

3.2 PORTB and the TRISB Register

PORTB is an 8-bit wide bi-directional port. The corresponding data direction register is TRISB. Setting a TRISB bit (=1) will make the corresponding PORTB pin an input, i.e., put the corresponding output driver in a hi-impedance mode. Clearing a TRISB bit (=0) will make the corresponding PORTB pin an output, i.e., put the contents of the output latch on the selected pin.

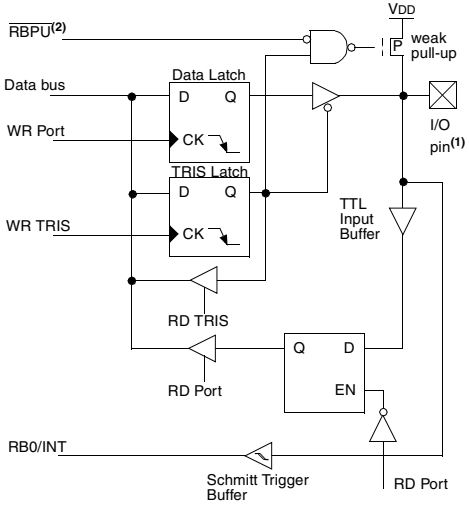
EXAMPLE 3-1: INITIALIZING PORTB

```
BCF     STATUS, RP0  ;
CLRF    PORTB        ; Initialize PORTB by
                     ; clearing output
                     ; data latches
BSF     STATUS, RP0  ; Select Bank 1
MOVLW   0xCF         ; Value used to
                     ; initialize data
                     ; direction
MOVWF   TRISB        ; Set RB<3:0> as inputs
                     ; RB<5:4> as outputs
                     ; RB<7:6> as inputs
```

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit $\overline{\text{RBPU}}$ (OPTION_REG<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset.

The RB0 pin is multiplexed with the external interrupt (RB0/INT).

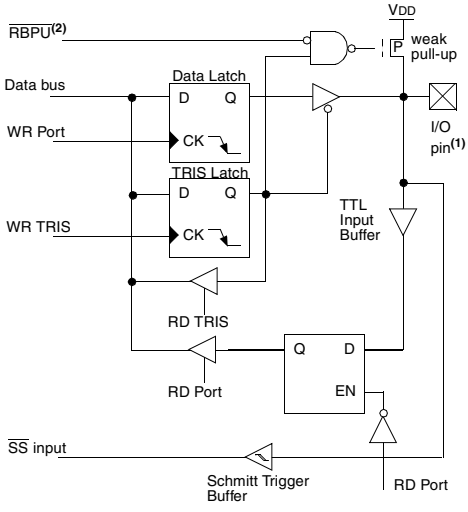
FIGURE 3-4: BLOCK DIAGRAM OF RB0 PIN



Note 1: I/O pins have diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit (OPTION_REG<7>).

The RB1 pin is multiplexed with the SSP module slave select (RB1/$\overline{\text{SS}}$).

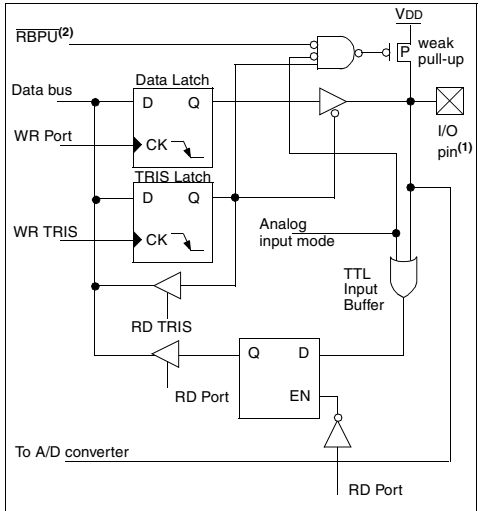
FIGURE 3-5: BLOCK DIAGRAM OF RB1/$\overline{\text{SS}}$ PIN



Note 1: I/O pins have diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit (OPTION_REG<7>).

The RB2 pin is multiplexed with analog channel 8 (RB2/AN8).

FIGURE 3-6: BLOCK DIAGRAM OF RB2/AN8 PIN



Note 1: I/O pins have diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit (OPTION_REG<7>).

3.3 PORTC and the TRISC Register

PORTC is an 8-bit wide bi-directional port. The corresponding data direction register is TRISC. Setting a TRISC bit (=1) will make the corresponding PORTC pin an input, i.e., put the corresponding output driver in a hi-impedance mode. Clearing a TRISC bit (=0) will make the corresponding PORTC pin an output, i.e., put the contents of the output latch on the selected pin.

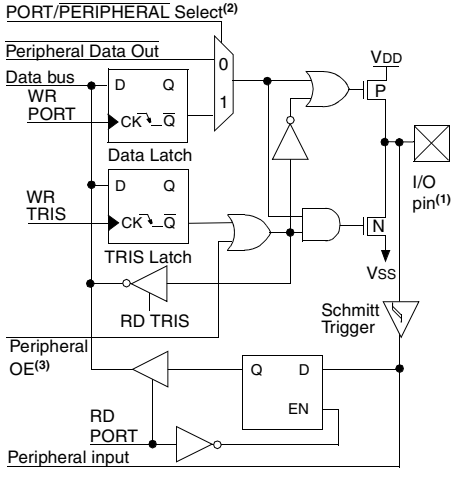
PORTC is multiplexed with several peripheral functions (Table 3-5). PORTC pins have Schmitt Trigger input buffers.

When enabling peripheral functions, care should be taken in defining TRIS bits for each PORTC pin. Some peripherals override the TRIS bit to make a pin an output, while other peripherals override the TRIS bit to make a pin an input. Since the TRIS bit override is in effect while the peripheral is enabled, read-modify-write instructions (`BSF, BCF, XORWF`) with TRISC as destination should be avoided. The user should refer to the corresponding peripheral section for the correct TRIS bit settings.

EXAMPLE 3-1: INITIALIZING PORTC

```
BCF     STATUS, RP0   ; Select Bank 0
CLRF    PORTC         ; Initialize PORTC by
                      ; clearing output
                      ; data latches
BSF     STATUS, RP0   ; Select Bank 1
MOVLW   0xCF          ; Value used to
                      ; initialize data
                      ; direction
MOVWF   TRISC         ; Set RC<3:0> as inputs
                      ; RC<5:4> as outputs
                      ; RC<7:6> as inputs
```

FIGURE 3-9: PORTC BLOCK DIAGRAM (PERIPHERAL OUTPUT OVERRIDE)



Note 1: I/O pins have diode protection to VDD and VSS.
2: Port/Peripheral select signal selects between port data and peripheral output.
3: Peripheral OE (output enable) is only activated if peripheral select is active.

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3.6 Parallel Slave Port

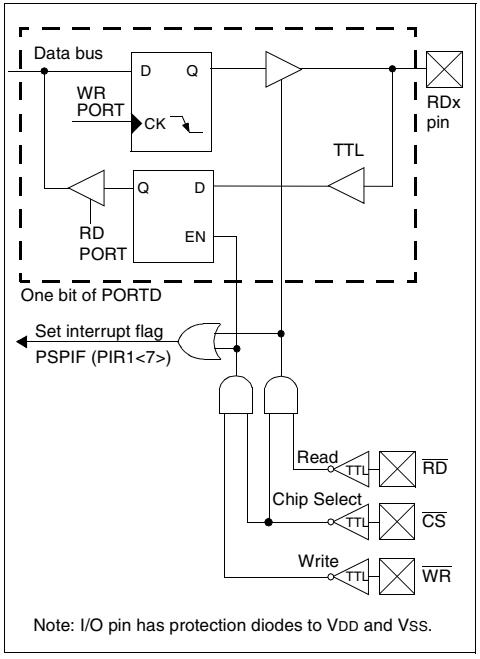
The Parallel Slave Port is implemented on the 40/44-pin devices only.

PORTD operates as an 8-bit wide Parallel Slave Port, or microprocessor port when control bit PSPMODE (TRISE<4>) is set. In slave mode it is asynchronously readable and writable by the external world through $\overline{RD}$ control input pin RE0/$\overline{RD}$ and $\overline{WR}$ control input pin RE1/$\overline{WR}$.

It can directly interface to an 8-bit microprocessor data bus. The external microprocessor can read or write the PORTD latch as an 8-bit latch. Setting bit PSPMODE enables port pin RE0/$\overline{RD}$ to be the $\overline{RD}$ input, RE1/$\overline{WR}$ to be the $\overline{WR}$ input and RE2/$\overline{CS}$ to be the $\overline{CS}$ (chip select) input. For this functionality, the corresponding data direction bits of the TRISE register (TRISE<2:0>) must be configured as inputs (set). The configuration bits, PCFG3:PCFG0 (ADCON1<3:0>) must be configured to make pins RE2:RE0 as digital I/O.

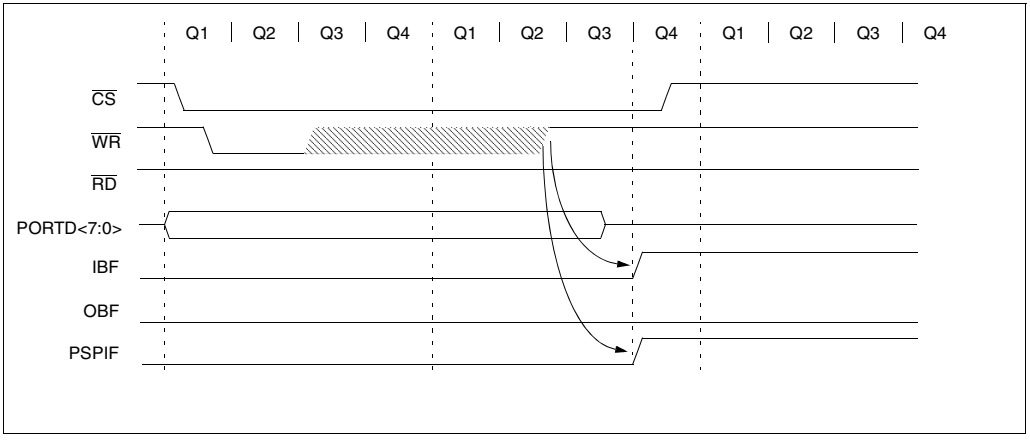
A write to the PSP occurs when both the $\overline{CS}$ and $\overline{WR}$ lines are first detected low. A read from the PSP occurs when both the $\overline{CS}$ and $\overline{RD}$ lines are first detected low.

FIGURE 3-13: PORTD AND PORTE BLOCK DIAGRAM (PARALLEL SLAVE PORT)



Note: I/O pin has protection diodes to VDD and VSS.

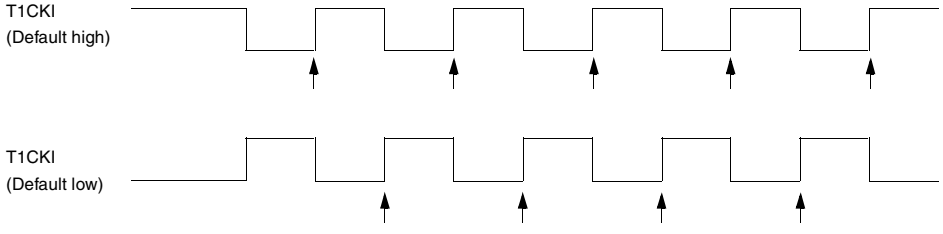
FIGURE 3-14: PARALLEL SLAVE PORT WRITE WAVEFORMS



5.1.1 TIMER1 COUNTER OPERATION

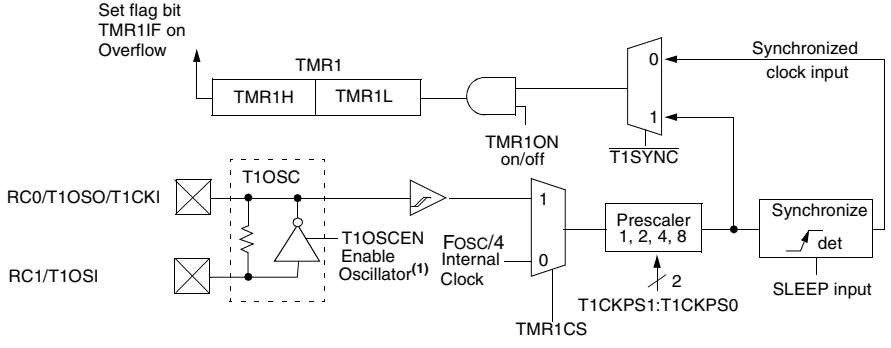
In this mode, Timer1 is being incremented via an external source. Increments occur on a rising edge. After Timer1 is enabled in counter mode, the module must first have a falling edge before the counter begins to increment.

FIGURE 5-2: TIMER1 INCREMENTING EDGE



Note: Arrows indicate counter increments.

FIGURE 5-3: TIMER1 BLOCK DIAGRAM



Note 1: When the T1OSCEN bit is cleared, the inverter and feedback resistor are turned off. This eliminates power drain.

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7.0 CAPTURE/COMPARE/PWM (CCP) MODULE(S)

Each CCP (Capture/Compare/PWM) module contains a 16-bit register which can operate as a 16-bit capture register, as a 16-bit compare register or as a PWM master/slave Duty Cycle register. Table 7-1 shows the timer resources of the CCP module modes.

The operation of CCP1 is identical to that of CCP2, with the exception of the special trigger. Therefore, operation of a CCP module in the following sections is described with respect to CCP1.

Table 7-2 shows the interaction of the CCP modules.

CCP1 Module

Capture/Compare/PWM Register1 (CCPR1) is comprised of two 8-bit registers: CCPR1L (low byte) and CCPR1H (high byte). The CCP1CON register controls the operation of CCP1. All are readable and writable.

CCP2 Module

Capture/Compare/PWM Register2 (CCPR2) is comprised of two 8-bit registers: CCPR2L (low byte) and CCPR2H (high byte). The CCP2CON register controls the operation of CCP2. All are readable and writable.

Additional information on the CCP module is available in the PICmicro™ Mid-Range Reference Manual, (DS33023).

TABLE 7-1 CCP MODE - TIMER RESOURCE

CCP Mode	Timer Resource
Capture	Timer1
Compare	Timer1
PWM	Timer2

TABLE 7-2 INTERACTION OF TWO CCP MODULES

CCPx Mode	CCPy Mode	Interaction
Capture	Capture	Same TMR1 time-base.
Capture	Compare	The compare should be configured for the special event trigger, which clears TMR1.
Compare	Compare	The compare(s) should be configured for the special event trigger, which clears TMR1.
PWM	PWM	The PWMs will have the same frequency, and update rate (TMR2 interrupt).
PWM	Capture	None
PWM	Compare	None

FIGURE 7-1: CCP1CON REGISTER (ADDRESS 17h) / CCP2CON REGISTER (ADDRESS 1Dh)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	CCPxX	CCPxY	CCPxM3	CCPxM2	$\overline{\text{CCPxM1}}$	$\overline{\text{CCPxM0}}$
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n =Value at POR reset

bit 7-6: **Unimplemented:** Read as '0'

bit 5-4: **CCPxX:CCPxY**: PWM Least Significant bits
Capture Mode: Unused
Compare Mode: Unused
PWM Mode: These bits are the two LSbs of the PWM duty cycle. The eight MSbs are found in CCPRxL.

bit 3-0: **CCPxM3:CCPxM0**: CCPx Mode Select bits
0000 = Capture/Compare/PWM off (resets CCPx module)
0100 = Capture mode, every falling edge
0101 = Capture mode, every rising edge
0110 = Capture mode, every 4th rising edge
0111 = Capture mode, every 16th rising edge
1000 = Compare mode, set output on match (CCPxIF bit is set)
1001 = Compare mode, clear output on match (CCPxIF bit is set)
1010 = Compare mode, generate software interrupt on match (CCPxIF bit is set, CCPx pin is unaffected)
1011 = Compare mode, trigger special event (CCPxIF bit is set; CCP1 resets TMR1; CCP2 resets TMR1 and starts an A/D conversion (if A/D module is enabled))
11xx = PWM mode

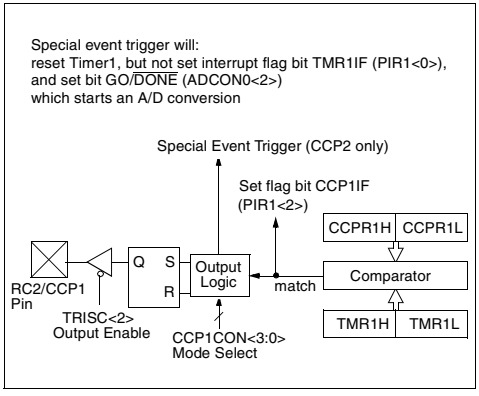
7.2 Compare Mode

In Compare mode, the 16-bit CCPR1 register value is constantly compared against the TMR1 register pair value. When a match occurs, the RC2/CCP1 pin is:

- driven High
- driven Low
- remains Unchanged

The action on the pin is based on the value of control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). At the same time, interrupt flag bit CCP1IF is set.

FIGURE 7-3: COMPARE MODE OPERATION BLOCK DIAGRAM



7.2.1 CCP PIN CONFIGURATION

The user must configure the RC2/CCP1 pin as an output by clearing the TRISC<2> bit.

Note:	Clearing the CCP1CON register will force the RC2/CCP1 compare output latch to the default low level. This is not the data latch.

7.2.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode if the CCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

7.2.3 SOFTWARE INTERRUPT MODE

When generate software interrupt is chosen the CCP1 pin is not affected. Only a CCP interrupt is generated (if enabled).

7.2.4 SPECIAL EVENT TRIGGER

In this mode, an internal hardware trigger is generated which may be used to initiate an action.

The special event trigger output of CCP1 resets the TMR1 register pair. This allows the CCPR1 register to effectively be a 16-bit programmable period register for Timer1.

The special trigger output of CCP2 resets the TMR1 register pair, and starts an A/D conversion (if the A/D module is enabled).

Note:	The special event trigger from the CCP2 module will not set interrupt flag bit TMR1IF (PIR1<0>).

TABLE 7-3 REGISTERS ASSOCIATED WITH CAPTURE, COMPARE, AND TIMER1

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111
0Eh	TMR1L	Holding register for the Least Significant Byte of the 16-bit TMR1 register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding register for the Most Significant Byte of the 16-bit TMR1register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	--00 0000	--uu uuuu
15h	CCPR1L	Capture/Compare/PWM register1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM register1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by Capture and Timer1.
Note 1: Bits PSPIE and PSPIF are reserved on the 28-pin, always maintain these bits clear.

FIGURE 8-24: REPEATED START CONDITION FLOWCHART (PAGE 2)

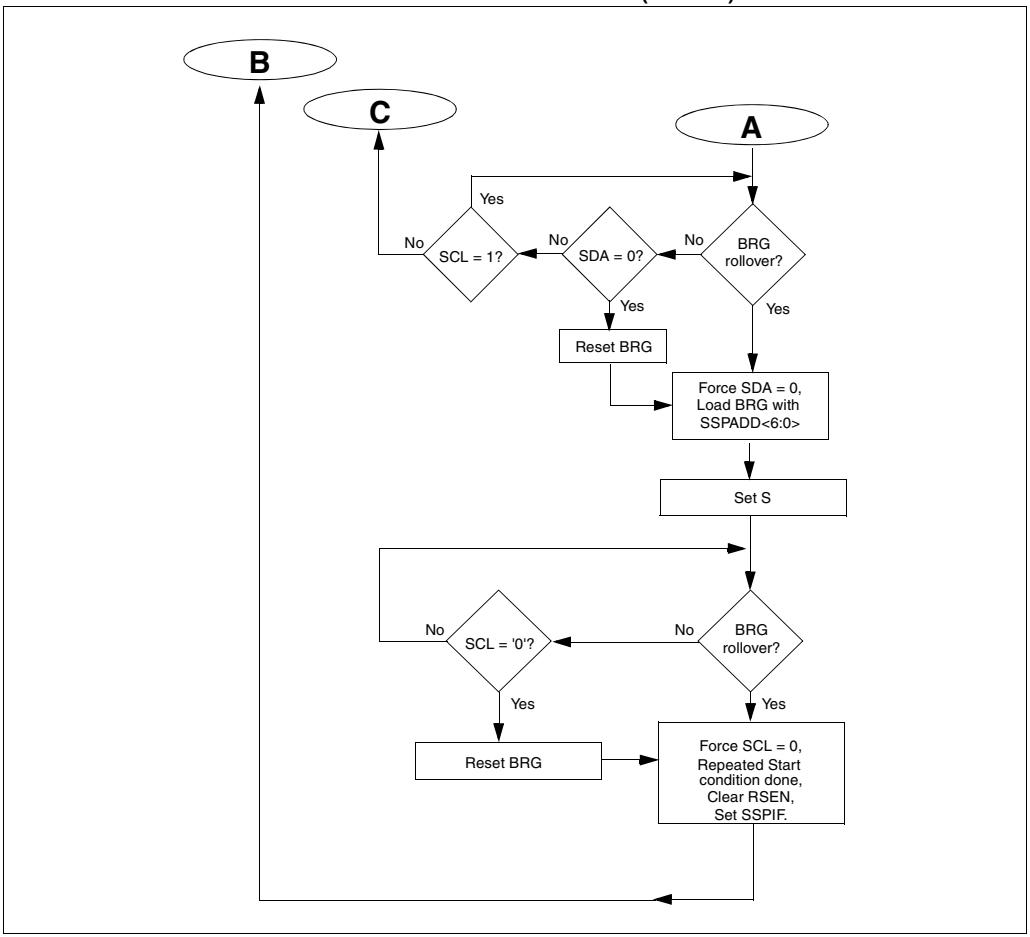


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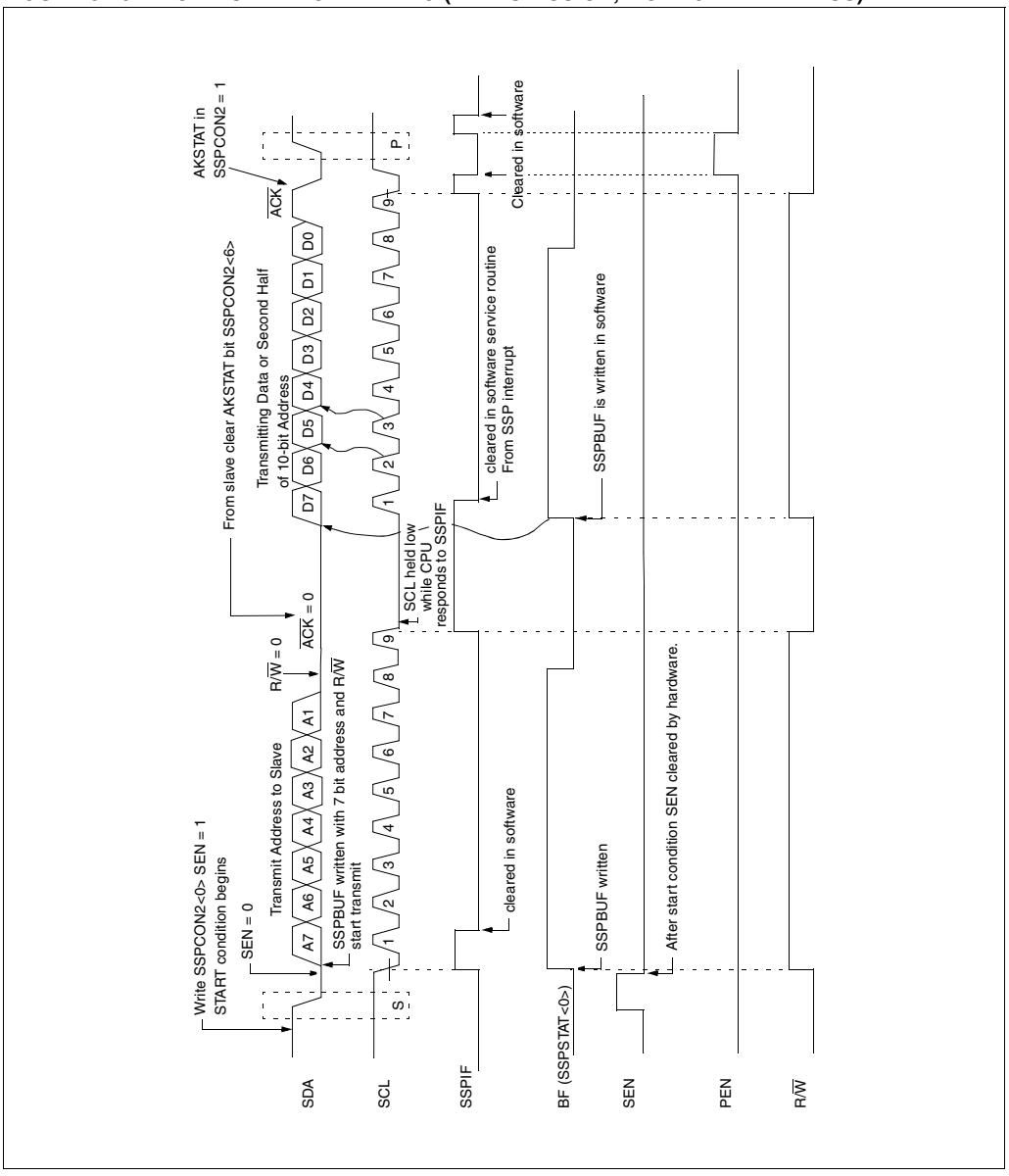
FIGURE 8-26: I²C MASTER MODE TIMING (TRANSMISSION, 7 OR 10-BIT ADDRESS)



8.2.12 I²C MASTER MODE RECEPTION

Master mode reception is enabled by programming the receive enable bit, RCEN (SSPCON2<3>).

Note:	The SSP Module must be in an IDLE STATE before the RCEN bit is set, or the RCEN bit will be disregarded.

The baud rate generator begins counting, and on each rollover, the state of the SCL pin changes (high to low/ low to high) and data is shifted into the SSPSR. After the falling edge of the eighth clock, the receive enable flag is automatically cleared, the contents of the SSPSR are loaded into the SSPBUF, the BF flag is set, the SSPIF is set, and the baud rate generator is suspended from counting, holding SCL low. The SSP is now in IDLE state, awaiting the next command. When the buffer is read by the CPU, the BF flag is automatically cleared. The user can then send an acknowledge bit at the end of reception, by setting the acknowledge sequence enable bit, AKEN (SSPCON2<4>).

8.2.12.10 BF STATUS FLAG

In receive operation, BF is set when an address or data byte is loaded into SSPBUF from SSPSR. It is cleared when SSPBUF is read.

8.2.12.11 SSPOV STATUS FLAG

In receive operation, SSPOV is set when 8 bits are received into the SSPSR, and the BF flag is already set from a previous reception.

8.2.12.12 WCOL STATUS FLAG

If the user writes the SSPBUF when a receive is already in progress (i.e. SSPSR is still shifting in a data byte), then WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

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TABLE 9-5 BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 1)

BAUD RATE (K)	FOSC = 20 MHz			16 MHz			10 MHz			7.16 MHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
9.6	9.615	+0.16	129	9.615	+0.16	103	9.615	+0.16	64	9.520	-0.83	46
19.2	19.230	+0.16	64	19.230	+0.16	51	18.939	-1.36	32	19.454	+1.32	22
38.4	37.878	-1.36	32	38.461	+0.16	25	39.062	+1.7	15	37.286	-2.90	11
57.6	56.818	-1.36	21	58.823	+2.12	16	56.818	-1.36	10	55.930	-2.90	7
115.2	113.636	-1.36	10	111.111	-3.55	8	125	+8.51	4	111.860	-2.90	3
250	250	0	4	250	0	3	NA	-	-	NA	-	-
625	625	0	1	NA	-	-	625	0	0	NA	-	-
1250	1250	0	0	NA	-	-	NA	-	-	NA	-	-

BAUD RATE (K)	FOSC = 5.068 MHz			4 MHz			3.579 MHz			1 MHz			32.768 kHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
9.6	9.6	0	32	NA	-	-	9.727	+1.32	22	8.928	-6.99	6	NA	-	-
19.2	18.645	-2.94	16	1.202	+0.17	207	18.643	-2.90	11	20.833	+8.51	2	NA	-	-
38.4	39.6	+3.12	7	2.403	+0.13	103	37.286	-2.90	5	31.25	-18.61	1	NA	-	-
57.6	52.8	-8.33	5	9.615	+0.16	25	55.930	-2.90	3	62.5	+8.51	0	NA	-	-
115.2	105.6	-8.33	2	19.231	+0.16	12	111.860	-2.90	1	NA	-	-	NA	-	-
250	NA	-	-	NA	-	-	223.721	-10.51	0	NA	-	-	NA	-	-
625	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
1250	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-

FIGURE 9-4: ASYNCHRONOUS TRANSMISSION

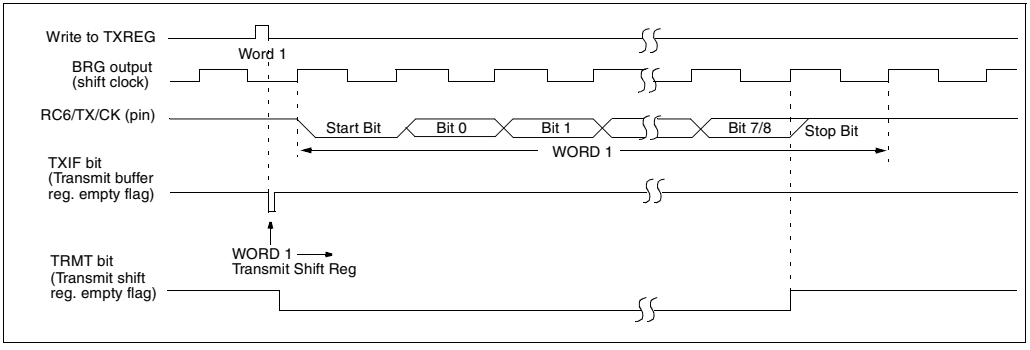
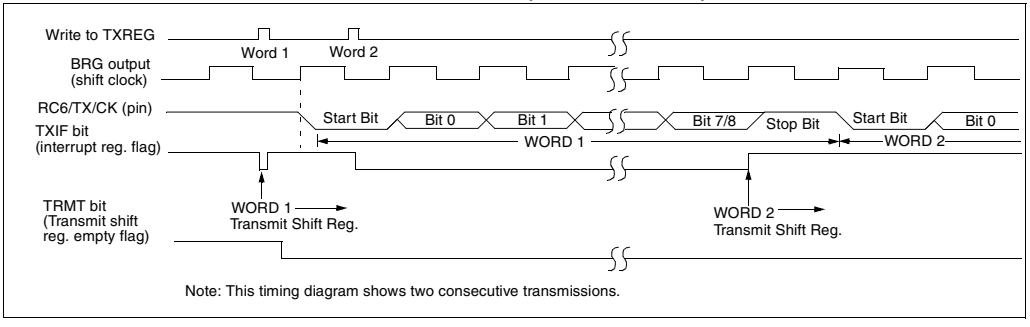


FIGURE 9-5: ASYNCHRONOUS TRANSMISSION (BACK TO BACK)



Note: This timing diagram shows two consecutive transmissions.

TABLE 9-6 REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
19h	TXREG	USART Transmit Register								0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for Asynchronous Transmission.
Note 1: Bits PSPIE and PSPIF are reserved on the 28-pin devices, always maintain these bits clear.

The value that is in the ADRESH and ADRESL registers are not modified for a Power-on Reset. The ADRESH and ADRESL registers will contain unknown data after a Power-on Reset.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as an input. To determine acquisition time, see Section 11.6. After this acquisition time has elapsed the A/D conversion can be started. The following steps should be followed for doing an A/D conversion:

11.2 Configuring the A/D Module

11.3 Configuring Analog Port Pins

The ADCON1 and TRIS registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bit set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS3:CHS0 bits and the TRIS bits.

Note 1:	When reading the PORTA or PORTE register, all pins configured as analog input channels will read as cleared (a low level). When reading the PORTB register, all pins configured as analog input channels will read as set (a high level). Pins configured as digital inputs, will convert an analog input. Analog levels on a digitally configured input will not affect the conversion accuracy.
Note 2:	Analog levels on any pin that is defined as a digital input (including the ANx pins), may cause the input buffer to consume current that is out of the devices specification.

11.3.1 CONFIGURING THE REFERENCE VOLTAGES

The VCFG bits in the ADCON1 register configure the A/D module reference inputs. The reference high input can come from an internal reference (VRH) or (VRL), an external reference (VREF+), or AVDD. The low reference input can come from an internal reference (VRL), an external reference (VREF-), or AVSS. If an external reference is chosen for the reference high or reference low inputs, the port pin that multiplexes the incoming external references is configured as an analog input, regardless of the values contained in the A/D port configuration bits (PCFG3:PCFG0).

After the A/D module has been configured as desired. and the analog input channels have their corresponding TRIS bits selected for port inputs, the selected channel must be acquired before conversion is started. The A/D conversion cycle can be initiated by setting the GO/$\overline{\text{DONE}}$ bit. The A/D conversion begins, and lasts for 13TAD. The following steps should be followed for performing an A/D conversion:

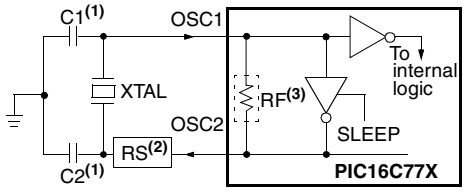
1. Configure the A/D module
   - Configure analog pins / voltage reference / and digital I/O (ADCON1)
   - Select A/D input channel (ADCON0)
   - Select A/D conversion clock (ADCON0)
   - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if required)
   - Clear ADIF bit
   - Set ADIE bit
   - Set PEIE bit
   - Set GIE bit
3. Wait the required acquisition time (3TAD)
4. Start conversion
   - Set GO/$\overline{\text{DONE}}$ bit (ADCON0)
5. Wait 13TAD until A/D conversion is complete, by either:
   - Polling for the GO/$\overline{\text{DONE}}$ bit to be cleared

   OR
   - Waiting for the A/D interrupt
6. Read A/D Result registers (ADRESH and ADRESL), clear ADIF if required.
7. For next conversion, go to step 1, step 2 or step 3 as required.

Clearing the GO/$\overline{\text{DONE}}$ bit during a conversion will abort the current conversion. The ADRESH and ADRESL registers **WILL** be updated with the partially completed A/D conversion value. That is, the ADRESH and ADRESL registers **WILL** contain the value of the current incomplete conversion.

Note:	Do not set the ADON bit and the GO/$\overline{\text{DONE}}$ bit in the same instruction. Doing so will cause the GO/$\overline{\text{DONE}}$ bit to be automatically cleared.

FIGURE 12-2: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



Note1: See Table 12-1 and Table 12-2 for recommended values of C1 and C2.
2: A series resistor (RS) may be required for AT strip cut crystals.
3: RF varies with the crystal chosen.

FIGURE 12-3: EXTERNAL CLOCK INPUT OPERATION (HS OSC CONFIGURATION)

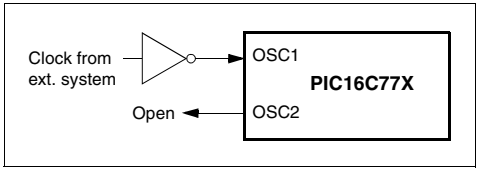


TABLE 12-1 CERAMIC RESONATORS

Ranges Tested:			
Mode	**Freq**	**OSC1**	**OSC2**
XT	455 kHz	68 - 100 pF	68 - 100 pF
	2.0 MHz	15 - 68 pF	15 - 68 pF
	4.0 MHz	15 - 68 pF	15 - 68 pF
HS	8.0 MHz	10 - 68 pF	10 - 68 pF
	16.0 MHz	10 - 22 pF	10 - 22 pF
These values are for design guidance only. See notes at bottom of page.			
Resonators Used:			
455 kHz	Panasonic EFO-A455K04B	± 0.3%	
2.0 MHz	Murata Erie CSA2.00MG	± 0.5%	
4.0 MHz	Murata Erie CSA4.00MG	± 0.5%	
8.0 MHz	Murata Erie CSA8.00MT	± 0.5%	
16.0 MHz	Murata Erie CSA16.00MX	± 0.5%	
All resonators used did not have built-in capacitors.			

TABLE 12-2 CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	**Crystal Freq**	**Cap. Range C1**	**Cap. Range C2**
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
These values are for design guidance only. See notes at bottom of page.			
Crystals Used			
32 kHz	Epson C-001R32.768K-A	± 20 PPM	
200 kHz	STD XTL 200.000KHz	± 20 PPM	
1 MHz	ECS ECS-10-13-1	± 50 PPM	
4 MHz	ECS ECS-40-20-1	± 50 PPM	
8 MHz	EPSON CA-301 8.000M-C	± 30 PPM	
20 MHz	EPSON CA-301 20.000M-C	± 30 PPM	

Note 1: Recommended values of C1 and C2 are identical to the ranges tested (Table 12-1).
2: Higher capacitance increases the stability of oscillator but also increases the start-up time.
3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.
4: Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification.

TABLE 12-6 INITIALIZATION CONDITIONS FOR ALL REGISTERS

Register	Devices		Power-on Reset, Brown-out Reset	MCLR Resets WDT Reset	Wake-up via WDT or Interrupt
W	773	774	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	773	774	N/A	N/A	N/A
TMR0	773	774	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	773	774	0000h	0000h	PC + 1(2)
STATUS	773	774	0001 1xxx	000q quuu(3)	uuuq quuu(3)
FSR	773	774	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	773	774	--0x 0000	--0u 0000	--uu uuuu
PORTB	773	774	xxxx 11xx	uuuu 11uu	uuuu uuuu
PORTC	773	774	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTD	773	774	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTE	773	774	---- -000	---- -000	---- -uuu
PCLATH	773	774	---0 0000	---0 0000	---u uuuu
INTCON	773	774	0000 000x	0000 000u	uuuu uuuu(1)
PIR1	773	774	r000 0000	r000 0000	ruuu uuuu(1)
	773	774	0000 0000	0000 0000	uuuu uuuu(1)
PIR2	773	774	0--- 0--0	0--- 0--0	u--- u--u(1)
TMR1L	773	774	xxxx xxxx	uuuu uuuu	uuuu uuuu
TMR1H	773	774	xxxx xxxx	uuuu uuuu	uuuu uuuu
T1CON	773	774	--00 0000	--uu uuuu	--uu uuuu
TMR2	773	774	0000 0000	0000 0000	uuuu uuuu
T2CON	773	774	-000 0000	-000 0000	-uuu uuuu
SSPBUF	773	774	xxxx xxxx	uuuu uuuu	uuuu uuuu
SSPCON	773	774	0000 0000	0000 0000	uuuu uuuu
CCPR1L	773	774	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR1H	773	774	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP1CON	773	774	--00 0000	--00 0000	--uu uuuu
RCSTA	773	774	0000 000x	0000 000x	uuuu uuuu
TXREG	773	774	0000 0000	0000 0000	uuuu uuuu
RCREG	773	774	0000 0000	0000 0000	uuuu uuuu
CCPR2L	773	774	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR2H	773	774	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP2CON	773	774	--00 0000	--00 0000	--uu uuuu
ADRESH	773	774	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON0	773	774	0000 0000	0000 0000	uuuu uuuu
OPTION_REG	773	774	1111 1111	1111 1111	uuuu uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition

Note 1: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

3: See Table 12-5 for reset value for specific condition.

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12.13 Power-down Mode (SLEEP)

Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the $\overline{PD}$ bit (STATUS<3>) is cleared, the $\overline{TO}$ (STATUS<4>) bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had, before the SLEEP instruction was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, place all I/O pins at either VDD, or VSS, ensure no external circuitry is drawing current from the I/O pin, power-down the A/D, disable external clocks. Pull all I/O pins, that are hi-impedance inputs, high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at VDD or VSS for lowest current consumption. The contribution from on-chip pull-ups on PORTB should be considered.

The $\overline{MCLR}$ pin must be at a logic high level (VIHMC).

12.13.1 WAKE-UP FROM SLEEP

The device can wake up from SLEEP through one of the following events:

1. External reset input on $\overline{MCLR}$ pin.
2. Watchdog Timer Wake-up (if WDT was enabled).
3. Interrupt from INT pin, RB port change, or some Peripheral Interrupts.

External $\overline{MCLR}$ Reset will cause a device reset. All other events are considered a continuation of program execution and cause a "wake-up". The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register can be used to determine the cause of device reset. The $\overline{PD}$ bit, which is set on power-up, is cleared when SLEEP is invoked. The $\overline{TO}$ bit is cleared if a WDT time-out occurred (and caused wake-up).

The following peripheral interrupts can wake the device from SLEEP:

1. PSP read or write.
2. TMR1 interrupt. Timer1 must be operating as an asynchronous counter.
3. CCP capture mode interrupt.
4. Special event trigger (Timer1 in asynchronous mode using an external clock).
5. SSP (Start/Stop) bit detect interrupt.
6. SSP transmit or receive in slave mode (SPI/I^2C).
7. USART RX or TX (synchronous slave mode).
8. A/D conversion (when A/D clock source is RC).
9. Low-voltage detect.

Other peripherals cannot generate interrupts since during SLEEP, no on-chip clocks are present.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

12.13.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the $\overline{TO}$ bit will not be set and $\overline{PD}$ bits will not be cleared.
- If the interrupt occurs **during or after** the execution of a SLEEP instruction, the device will immediately wake up from sleep. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the $\overline{TO}$ bit will be set and the $\overline{PD}$ bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

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NOTES:

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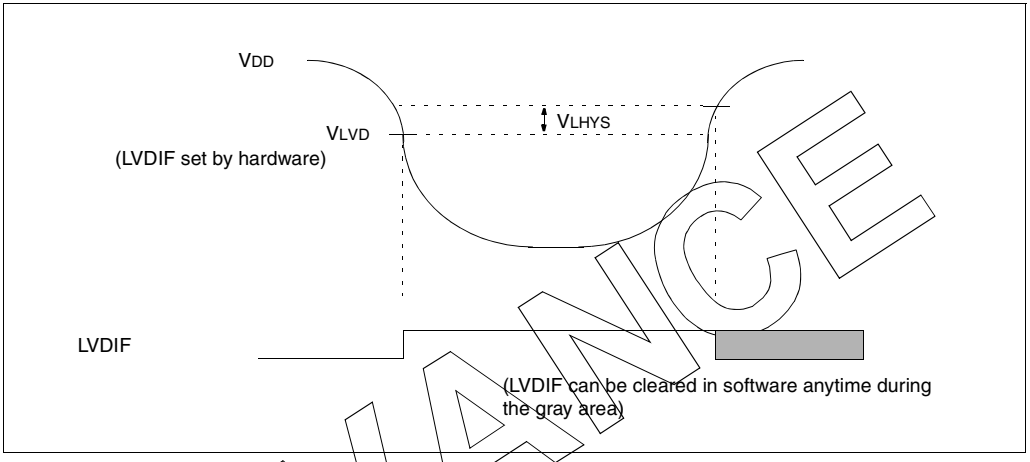
FIGURE 15-1: LOW-VOLTAGE DETECT CHARACTERISTICS



ADVANCE

TABLE 15-3 ELECTRICAL CHARACTERISTICS: LVD

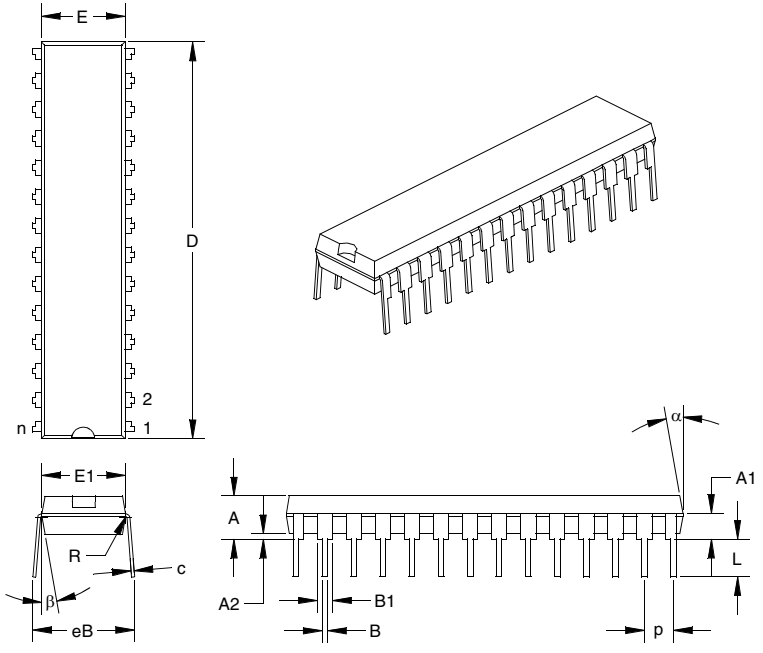
DC CHARACTERISTICS				**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in DC spec Section 15.1 and Section 15.2.				
Param No.	**Characteristic**		**Symbol**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D420	LVD Voltage	LVV = 0100		2.5	2.58	2.66	V	
		LVV = 0101		2.7	2.78	2.86	V	
		LVV = 0110		2.8	2.89	2.98	V	
		LVV = 0111		3.0	3.1	3.2	V	
		LVV = 1000		3.3	3.41	3.52	V	
		LVV = 1001		3.5	3.61	3.72	V	
		LVV = 1010		3.6	3.72	3.84	V	
		LVV = 1011		3.8	3.92	4.04	V	
		LVV = 1100		4.0	4.13	4.26	V	
		LVV = 1101		4.2	4.33	4.46	V	
		LVV = 1110		4.5	4.64	4.78	V	
D421	Supply Current		ΔILVD	—	10	20	μA	
D422*	LVD Voltage Drift Temperature coefficient		TCVOUT	—	15	50	ppm/°C	
D423*	LVD Voltage Drift with respect to VDD Regulation		ΔVLVD/ ΔVDD	—	—	50	μV/V	
D424*	Low-voltage Detect Hysteresis		VLHYS	TBD	—	100	mV	

* These parameters are characterized but not tested.

Note 1: Production tested at Tamb = 25°C. Specifications over temp limits ensured by characterization.

17.2 K04-070 28-Lead Skinny Plastic Dual In-line (SP) – 300 mil

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
PCB Row Spacing			0.300			7.62	
Number of Pins	n		28			28	
Pitch	p		0.100			2.54	
Lower Lead Width	B	0.016	0.019	0.022	0.41	0.48	0.56
Upper Lead Width	B1†	0.040	0.053	0.065	1.02	1.33	1.65
Shoulder Radius	R	0.000	0.005	0.010	0.00	0.13	0.25
Lead Thickness	c	0.008	0.010	0.012	0.20	0.25	0.30
Top to Seating Plane	A	0.140	0.150	0.160	3.56	3.81	4.06
Top of Lead to Seating Plane	A1	0.070	0.090	0.110	1.78	2.29	2.79
Base to Seating Plane	A2	0.015	0.020	0.025	0.38	0.51	0.64
Tip to Seating Plane	L	0.125	0.130	0.135	3.18	3.30	3.43
Package Length	D‡	1.345	1.365	1.385	34.16	34.67	35.18
Molded Package Width	E‡	0.280	0.288	0.295	7.11	7.30	7.49
Radius to Radius Width	E1	0.270	0.283	0.295	6.86	7.18	7.49
Overall Row Spacing	eB	0.320	0.350	0.380	8.13	8.89	9.65
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter.

† Dimension “B1” does not include dam-bar protrusions. Dam-bar protrusions shall not exceed 0.003” (0.076 mm) per side or 0.006” (0.152 mm) more than dimension “B1.”

‡ Dimensions “D” and “E” do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010” (0.254 mm) per side or 0.020” (0.508 mm) more than dimensions “D” or “E.”